

Amendments to the Specification:

Please replace the paragraphs on page 1, lines 14-27 with the following amended paragraphs (note that this section was also amended in the paper filed September 24, 2001):

This patent application is a divisional application which claims priority to pending application Serial No. 09/032,473 (status: abandoned), filed 26 Feb 1998, which claims the benefits of the following provisional application under 35 USC 119(e): commonly-owned copending U.S. Patent Application entitled "MICROELECTRONIC CONTACT STRUCTURES," Serial No. 60/073,679 filed 04 Feb 98 by Pedersen and Khandros, incorporated by reference herein.

Application Serial No. 09/032,473 ~~This patent application~~ is also a continuation-in-part of commonly-owned, copending U.S. Patent Application No. **08/852,152** filed 06 May 97 by Eldridge, Khandros, Mathieu and Pedersen (status: now U.S. Patent No. 6,184,053 pending) and its counterpart PCT Patent Application No. **US97/08634** filed 15 May 97 (status: published as **WO97/43654**, 20 Nov 97), both of which are incorporated by reference herein, both of which are referred to hereinafter as the "PARENT CASE".

Please replace the paragraph on page 2, lines 3-22 with the following amended paragraphs:

Commonly-owned, copending U.S. Patent Application No. **08/452,255** filed 26 May 95 by Eldridge, Grube, Khandros and Mathieu (status: now U.S. Patent No. 6,336,269 pending) and its counterpart PCT patent application number **PCT/US95/14909** filed 13 NOV 95 (status: published as **WO95/14909**, 06 Jun 96) disclose methods for making resilient interconnection elements for microelectronics applications involving mounting an end of a flexible elongate core element (e.g., wire "stem" or "skeleton") to a terminal on an electronic component, coating the flexible core element and adjacent surface of the terminal with a "shell" of one or more materials having a predetermined combination of thickness, yield strength and elastic modulus to ensure predetermined force-to-deflection characteristics of the resulting spring contacts. Exemplary

materials for the core element include gold. Exemplary materials for the coating include nickel and its alloys. The resulting spring contact element may be used to effect pressure, or demountable, connections between two or more electronic components, particularly microelectronic components, including semiconductor devices.

Please replace the paragraph on page 3, lines 26 – page 4, line 15 with the following amended paragraph:

Commonly-owned, copending U.S. Patent Application No. **08/955,001** filed 20 Oct 97 by Eldridge, et al. (status: now U.S. Patent No. 6,043,563 ~~pending~~), incorporated by reference herein, also addresses and is particularly well-suited to making interconnections to modern microelectronic devices having their terminals (bond pads) disposed at a fine-pitch. As described therein, spring contact elements may be fabricated at areas on an electronic component which are remote from terminals to which they are electrically connected, and electrically connected to the terminals via conductive lines which extend from terminals of an electronic component to positions which are remote from the terminals. In this manner, a plurality of substantially identical spring contact elements can be mounted to the electronic component so that their free ends are disposed in a pattern and at positions which are spatially-translated from the pattern of the terminals on the component. The spring contact elements include, but are not limited to, composite interconnection elements and plated-up structures. The electronic component includes, but is not limited to, a semiconductor device, a memory chip, a portion of a semiconductor wafer, a space transformer, a probe card, a chip carrier, and a socket.

Please replace the paragraph on page 64, lines 5-20 with the following amended paragraphs:

Commonly-owned, copending U.S. Patent Application No. **08/819,464** filed 06 Mar 97 by Eldridge, et al. (status: abandoned~~pending~~) and its counterpart PCT Patent Application No. **US97/08606** filed 15 May 97 (status: published as **WO07/43653**, 20 Nov 97, discloses techniques for fabricating contact tip structures on a sacrificial substrate, mounting the pre-fabricated contact tip structures to ends of resilient contact structures, and removing the

sacrificial substrate. Such techniques could be employed, for example, with the contact structure 360 described hereinabove, to impart a topology to the tip end 362 of the contact structure.

The resulting contact structures can be heat-treated to tailor their mechanical properties, as disclosed in commonly-owned, copending U.S. Patent Application No. **08/931,923** filed 17 Sep 97 (status: abandoned~~pending~~).